

ABSTRACT

A method of combining components to form an integrated device, wherein at least one first component is provided on a first surface of a sacrificial substrate, and at least one second component is provided on a first surface of a non-sacrificial substrate. At least one support structure is formed on at least one of the first surfaces of the sacrificial substrate, and the non-sacrificial substrate, respectively, such that said at least one support structure is extended outwardly from at least one of the first surfaces. The sacrificial substrate carrying the first component, and the non-sacrificial substrate carrying the second component, respectively, are bonded, so that the first and second surfaces will be facing one another with a distance defined by a thickness of the support structure. At least a part of the sacrificial substrate is removed. The first component and second components are interconnected.